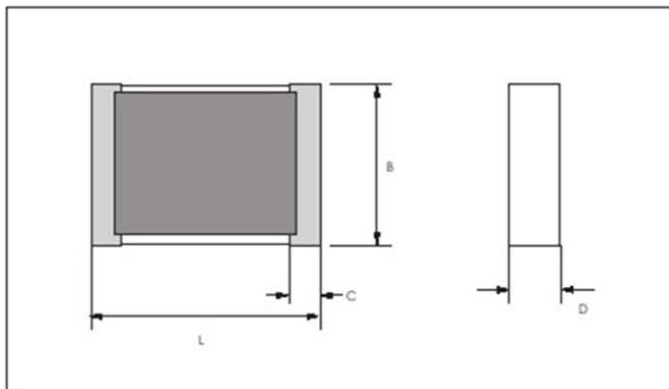




Construction



Features

- Thick film technology
- Close tolerance
- Low TCR

Dimensions(mm)

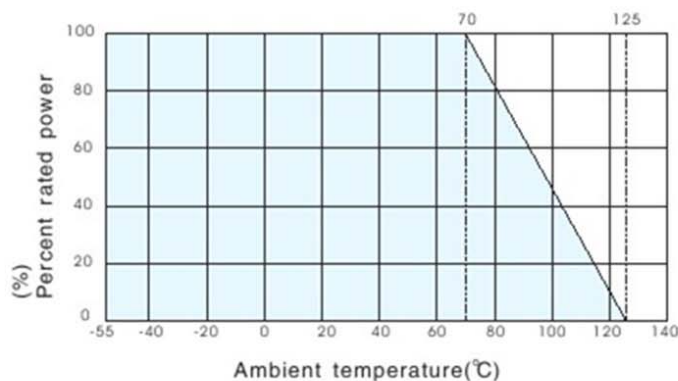
Type	L	B	D	C
PCR0805	2.00 ^{+0.10}	1.25 ^{+0.10}	0.50 ^{+0.10}	0.35 ^{+0.20}
PCR1206	3.10 ^{+0.10}	1.60 ^{+0.10}	0.55 ^{+0.10}	0.45 ^{+0.20}

L=Length, B=Width, D=Thickness,
C=Width of wraparound (in mm)

Applications

- Computers
- Telecom and wireless
- Precision meters and instruments
- Electrical devices

Derating Curve



Reference Standards

Q/ATK06-2005

Technical Specifications

Type	Power rating P ₇₀ (W)	TCR(ppm°C)	Resistance Range	Limiting Voltage (DC or AC Effective Value)	Resistance Tolerance(%)	Climatic Category
PCR0805	0.125	± 50	1R0~10M	100V	± 1%	55/125/56
PCR1206	0.25	± 25		200V	± 0.5%	
		± 15			± 0.25%	
					± 0.1%	

Special specifications can be supplied in consultation with customers.

Performance

Test item	Specifications	Test Methods
Rapid change of temperature	$\Delta R \leq \pm (0.25\%R + 0.05 \Omega)$	-55°C 30min / 125°C 30min, 5cycles
Temperature cycling	$\Delta R \leq \pm (1\%R + 0.05 \Omega)$	125°C, 16h / 55°C, RH93±3%, 24h / -55°C, 2h / 15~35°C, 8.5kpa, 1h
Endurance at 70°C	$\Delta R \leq \pm (1\%R + 0.05 \Omega)$	70±2°C, P _n , 1000h
Leaching	$\Delta R \leq \pm (0.25\%R + 0.05 \Omega)$	350±10°C, 3.5±0.5S
short time overload	$\Delta R \leq \pm (0.25\%R + 0.05 \Omega)$	2.5V _n , 5S
Damp heat, steady state	$\Delta R \leq \pm (1\%R + 0.05 \Omega)$	40°C, RH93±3%, 56d
Endurance at upper category temperature	$\Delta R \leq \pm (1\%R + 0.05 \Omega)$	125°C, 1000h
Solderability	≥95%	235±5°C, 2±0.5S

How To Order

Example

PCR	0805	125mW	100KΩ	±0.1%	±15ppm	tape/bag
Type	Style	Power	Nominal Value	Tolerance	TCK	Packaging
PCR	0805 1206	125mW 250mW	100MΩ	±0.1% ±0.25% ±0.5% ±1%	±15ppm ±25ppm ±50ppm	tape bag

If no requirements for TCR and taping are given, the standard value (highest value in table) will be supplied and packaging is bulk.

Recommended Mounting Methods

Generally, in the case of flow soldering, the soldering pad width should be 0.7 to 0.8 times the width of chip resistors. In the case of reflowing soldering, the soldering pad width should be 1.0 to 1.3 times the width of chip resistors.